Product End-of-Life Disassembly Instructions

Product Category: Desktop
Marketing Name / Model [List multiple models if applicable.]
Name / Model #1 HP ZGX Nano G1n AI Station

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	☒ Main board (MB) PCB ☒ Solid state drive (SSD) PCB ☒ Wireless WAN module (WWAN) PCB ☐ Touch module PCB ☐ Power supply PCB ☐ External Keyboard (KB) ☐ External Mouse ☐ Others: ______________	3
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	☒ RTC/CMOS battery ☐ Others: ______________	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: ☐ screws ☐ snaps ☐ adhesive ☐ other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0

HP Inc. instructions for this template are available at EL-MF877-01

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	☐ Panel LCD	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	☐ Power Supply capacitor(s) or condenser(s)	0
External electrical cables and cords	☒ AC power cord ☐ Audio, video or data cables ☐ Other: __________	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	Philip #0
Screwdriver	Philip #1
Screw Socket for Hex Nut/M3	Hex-socket/M3

3.0 Product Disassembly Process

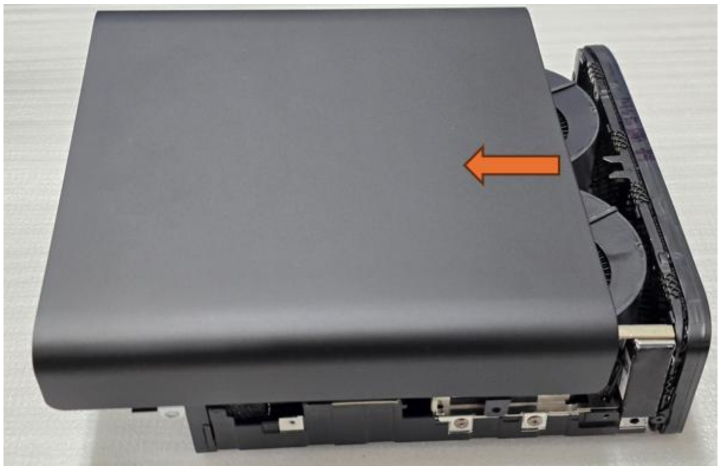
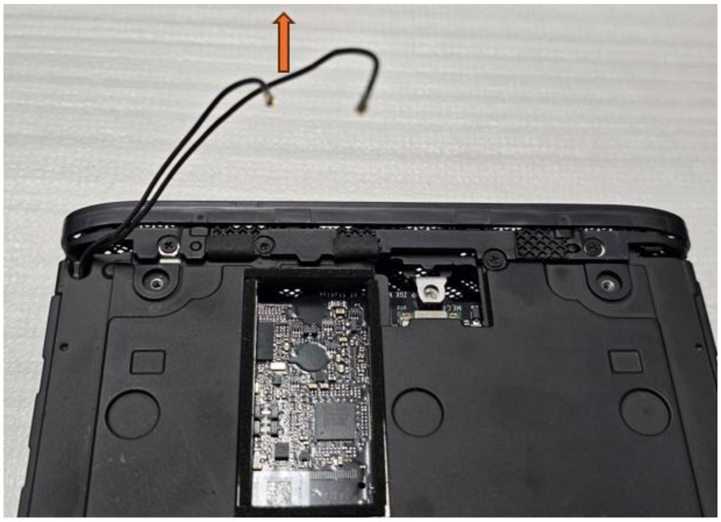
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

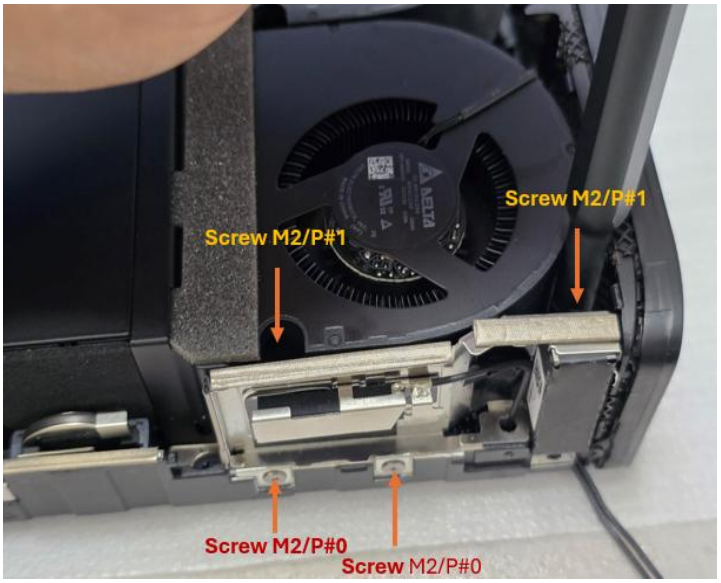
1. Remove BTM Feet from BTM Cover.
2. Loose BTM Cover Screws /Captive Screw x4pcs
3. Open BTM Cover, and take out.
4. Loose and remove Top Cover Screw M2/P#1 x4pcs.
5. Pull out Top cover by sliding toward Rear side.
6. Turn the System Unit to the Bottom side ,and Draw out the antenna Cable from the Base Pan Cable Recess.
7. Loose Screws secured on Antenna Cover/M2-P#1X 4 pcs.
8. Draw out the Antenna Cover from Chassis.
9. loose and remove screws x4 secured on Thermal Fan module
10. Loose and remove screws secured on Front Bezel/M2P#1x6
11. Rotate Clock-wide to remove Front_Bezel Assy from Base Pan Assy.
12. Dis-connect Thermal Fan Connector from PCA.
13. Draw-out Thermal Fan module from PCA.
14. . Loose and remove screws secured on Thermal Heat-sink Assy Screw M2/P#1x9, Hex Nut M3x1
15. Draw-out Thermal Heatsink module from PCA.
16. Loose and remove screws secured on PCA.-ScrewM2/P#1x4 PCS.
17. Draw-out PCA from Chassis.
18. Press Down the snaps on Rear Bezel ,and should be able to Dis-engaged it to Chassis ,and take out.
19. Press Down the snaps on P/W Switch Holder, and then should be able to take out it from Chassis.

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: End-of-Life Product Disassembly Instructions (hp.com)

1.Remove BTM Feet from BTM Cover.	**Photo 1** 
2. Loose BTM Cover Screws /Captive Screw x4	**Photo 2** 

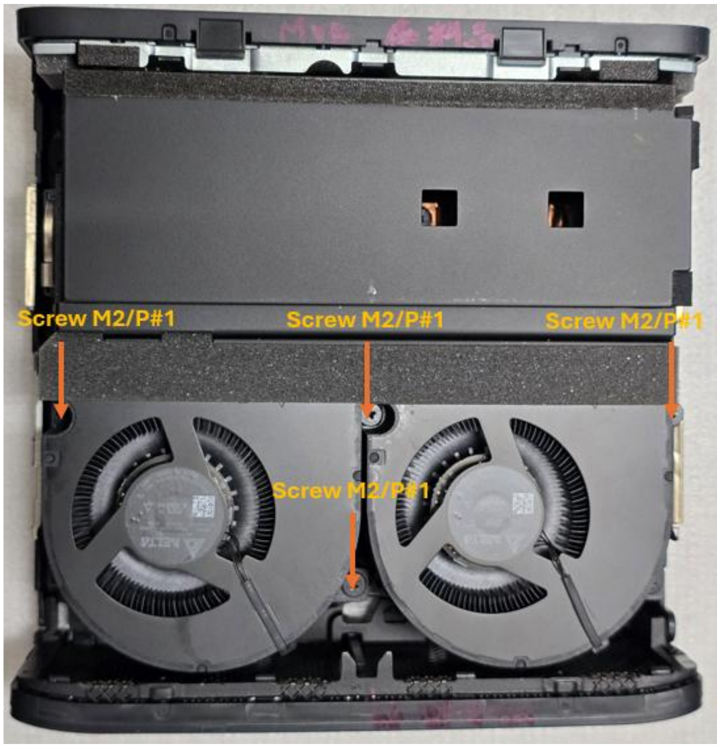
3. Open BTM Cover, and take out	**Photo 3** 
4. Loose and remove Top Cover Screw M2/P#0 x4pcs	**Photo 4**  **Photo 5** 

5. Pull out Top cover by sliding toward Rear side.	**Photo 6** 
6. Turn the System Unit to the bottom side, and draw out the antenna cable from the Base Pan Cable Recess.	**Photo 7** 

7. Loose Screws secured on Antenna Cover/M2-P#1X 4 pcs.	Photo 8 
8. Draw out the Antenna Cover from Chassis	Photo 9 

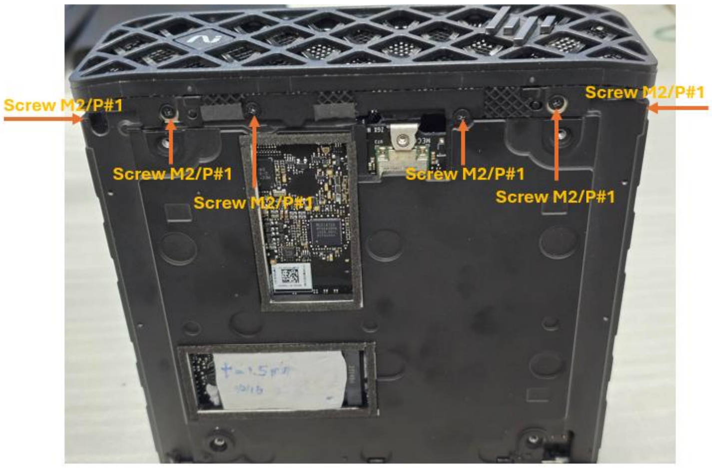
9. loose and remove screws x4 secured on Thermal Fan module

Photo 10



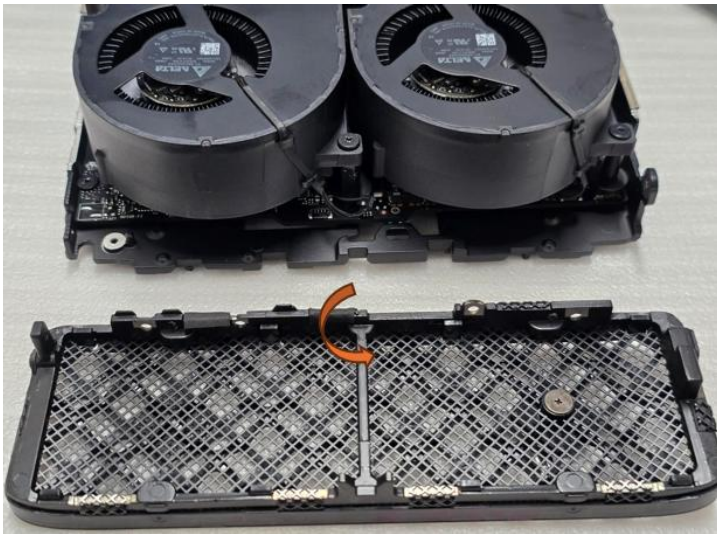
10. Loose and remove screws secured on Front Bezel/M2P#1x6

Photo 11



11. Rotate Clock-wide to remove Front Bezel Assy from Base Pan Assy

Photo 12

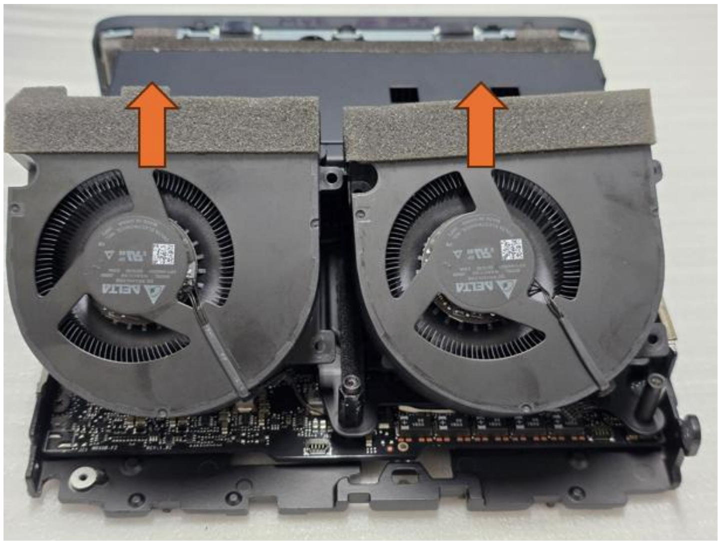


12. Dis-connect Thermal Fan Connector from PCA

Photo 13

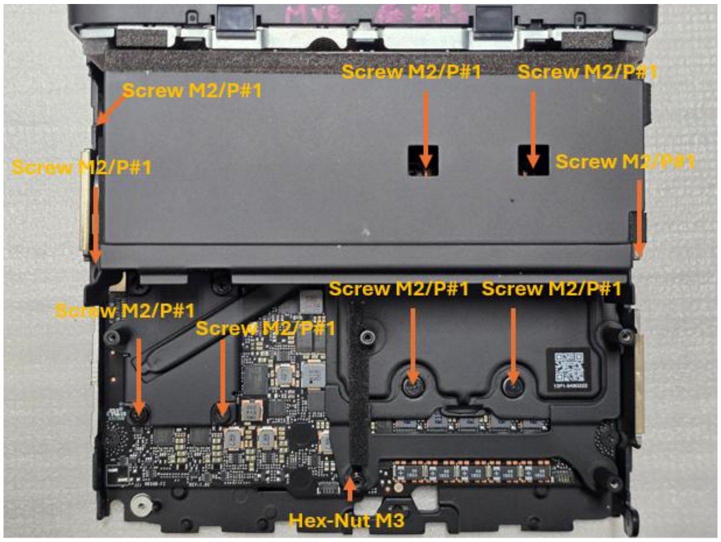
13. Draw-out Thermal Fan module from PCA

Photo 14



14. Loose and remove screws secured on Thermal Heat-sink Assy
    Screw M2/P#1x9, Hex Nut M3x1

Photo 15

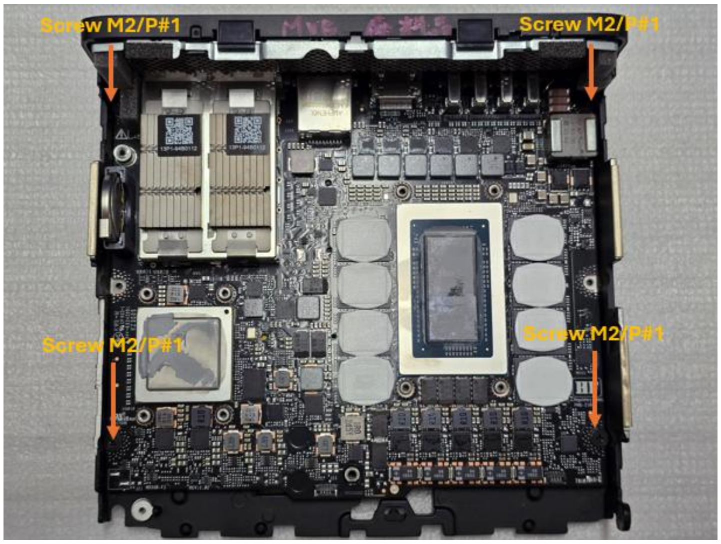


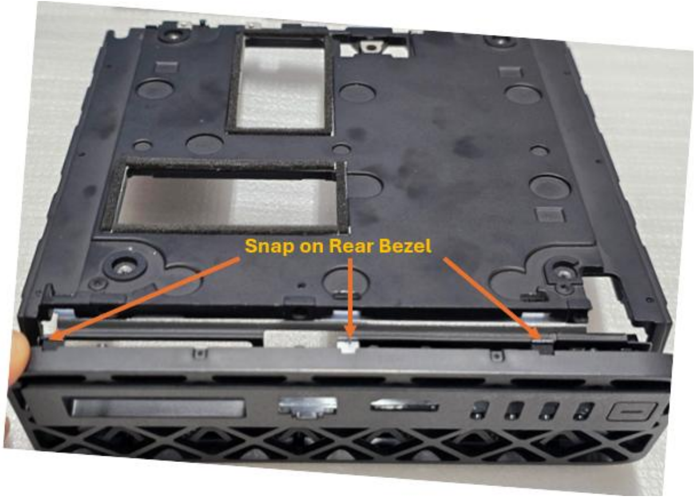
15. Draw-out Thermal Heatsink module from PCA.

Photo 16

16. Loose and remove screws secured on PCA.
M2/P#1x4 PCS

Photo 17



17. Draw-out PCA from Chassis.	**Photo 18** 
18. Press Down the snaps on Rear Bezel ,and should be able to Dis-engaged it to Chassis ,and take out.	**Photo 19** 

19. Press Down the snaps on P/W Switch Holder, and then should be able to take out it from Chassis.	**Photo 20**